REVISIONS																								
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SHEET			L																				T	T
REV	4_			L	<u> </u>	<u> </u>																	T	
SHEET	Щ.		<u> </u>			L			L	L												Π	Π	
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OF SHEETS	Sł	IEET		1	2	3	4	5	6	7	8	9	10	11								П		
STANDARI MILITAI DRAWII	RY NG AVAILA	NBLE		PREPARED BY CHECKED BY APPROVED DHAWING APPROVAL DATE 20 SEPTEMBER 1989				DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444 MICROCIRCUITS, DIGITAL, FAST, CMOS, OCTAL BUFFER/LINE DRIVER WITH THREE-STATE OUTPUT, MONOLITHIC SILICON				AL												
FOR USE BY ALL DI AND AGENCIES DEPARTMENT OF AMSC N/A	OF TH	ΙE	5		20 S			R 19	989			+	SIZE A S	HEE	6	72	68		OF		62 -	8 9	73.	2

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5962-E1431

DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.

SCOPE 1.1 Scope. This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices". 1.2 Part number. The complete part number shall be as shown in the following example: 5962-89732 Drawing number Device type Case outline Lead finish per (1.2.1)(1.2.2)MIL-M-38510 1.2.1 Device types. The device types shall identify the circuit function as follows: Device type Generic number Circuit function 01 54FCT241 Octal buffer/line driver with three-state output, TTL compatible 54FCT241A Octal buffer/line driver with three-state output, TTL compatible 1.2.2 Case outlines. The case outlines shall be as designated in appendix C of MIL-M-38510, and as follows: Outline letter Case outline D-8 (20-lead, 1.060" x .310" x .200"), dual-in-line package F-5 (20-lead, .540" x .300" x .100"), flat package C-2 (20-terminal, .358" x .358" x .100"), square chip carrier package R 1.3 Absolute maximum ratings. 1/ - -0.5 V dc to +7.0 V dc -0.5 V dc to V_{CC} + 0.5 V dc -0.5 V dc to V_{CC} + 0.5 V dc DC output current ------±100 mA -20 mA -50 mA 500 mW See MIL-M-38510, appendix C -65°C to +150°C +175°C +300°C 1.4 Recommended operating conditions. +4.5 V dc to +5.5 V dc 0.8 V dc 2.0 V dc -55°C to +125°C All voltages referenced to GND.

1/ All voltages referenced to GND. 2/ Must withstand the added PD due to short circuit test; e.g., I_{OS} .

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2. APPLICABLE DOCUMENTS

2.1 Government specification, standard, and bulletin. Unless otherwise specified, the following specification, standard, and bulletin of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

MILITARY

MIL-M-38510 - Microcircuits, General Specification for.

STANDARD

MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics.

BULLETIN

MILITARY

MIL-BUL-103 - List of Standardized Military Drawings (SMD's).

(Copies of the specification, standard, and bulletin required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

3. REQUIREMENTS

- 3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.
- 3.2 <u>Design</u>, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.
 - 3.2.1 Terminal connections. The terminal connections shall be as specified on figure 1.
 - 3.2.2 <u>Truth table</u>. The truth table shall be as specified on figure 2.
 - 3.2.3 Logic diagram. The logic diagram shall be as specified on figure 3.
 - 3.2.4 <u>Case outlines</u>. The case outlines shall be in accordance with 1.2.2 herein.
- 3.3 Electrical performance characteristics. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and apply over the full case operating temperature range.
- 3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.
- 3.5 Marking. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the part number listed in 1.2 herein. In addition, the manufacturer's part number may also be marked as listed in MIL-BUL-103 (see 6.6 herein).

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	T	E I. Electr	pc//		uc	T				·	
Test	Symbol						Group A	Lim	l ∐ Uni		
All 1-1-1-1-1-1-1-1-1-1-1-1-1-1-1-1-1-1-1		-55°C < T _C < +125°C V _{CC} = 5.0 V dc ±10% unless otherwise specified			fied	type 	subgroups 	l Min 	Max		
High level output voltage	evel output V_{OH} $V_{CC} = 4$ age $V_{IL} = 0$		V _{CC} = 4.5 V, V _{IL} = 0.8 V, V _{IH} = 2.0 V			All	1, 2, 3	4.3		V	
	! 	i = 2.0 v	IH = 2.0 V		-12 mA	 A11 	1, 2, 3	2.4	 	 	
Low level output voltage	V _{OL}	V _{CC} = 4.5 V, V _{IL} = 0.8 V, V _{IH} = 2.0 V	•	I _{OL} =	300 μΑ	 A11 	 1, 2, 3 	 	0.2	 V 	
		 		I _{OL} =	48 mA	 All 	1, 2, 3	 	0.5	T 	
Input clamp voltage	VIK	V _{CC} = 4.5 V, I _{IN} = -18 mA			A11	1, 2, 3	! !	-1.2	i V		
High level input current	 I IH 	 V _{CC} = 5.5 V, V _{IN} = 5.5 V			 A11 	1, 2, 3	 	 5.0	 μ Α		
Low level input current	IIL	V _{CC} = 5.5 V, V _{IN} = GND			A11	1, 2, 3		-5.0	μA		
High impedence output current	I OZH	V _{CC} = 5.5 V, V _{IN} = 5.5 V			A11	1, 2, 3	 	10	LμA		
	IozL	!V _{CC} = 5.5 V, V _{IN} = GND				All	1, 2, 3		 -10	l LμA	
Short circuit output current	I I OS	 V _{CC} = 5.5 V V _O = GND	<u>1</u> /			 A11 	1, 2, 3	 -60 	! ! !	l lmA l	
Quiescent power supply current (CMOS inputs)	I _{CCQ}	V _{IN} < 0.2 V V _{CC} = 5.5 V,	or V _{IN} ≥ 6 M	5.3 V, Hz		A11	1, 2, 3		1.5	mA	
Quiescent power supply current (TTL inputs)	ΔICC	V _{CC} = 5.5 V,	V _{IN} = 3.	4 V <u>2</u> /		All	1, 2, 3		2.0	mA	
Dynamic power supply current		V_{CC} = 5.5 V, $\overline{OE}n$ = GND, one bit toggling, 50% duty cycle, $V_{IN} \geq$ 5.3 V or $V_{IN} \leq$ 0.2 V, outputs open			cycle, i	A11	<u>3/</u>		0.25	mA/ MHz	
See footnotes at end of	ftable		A Maria and A		-						
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Т.	ABLE I.	Electrical performa	nce characteris	tics - 0	Continued.			
Test	Symbo1	Condition		Group A	Lim	Unit		
		-55 C < 1C < V _{CC} = 5.0 V unless otherwi	$-55^{\circ}C < T_C < +125^{\circ}C$ $V_{CC} = 5.0 \text{ V dc } \pm 10\%$ unless otherwise specified			Min	 Max 	[
Total power supply current	Icc	 V _{CC} = 5.5 V, outputs open, f _I = 10 MHz, 50% duty cycle,	$\begin{vmatrix} V_{\text{IN}} \ge 5.3 \text{ V} \\ \text{or} \\ V_{\text{IN}} \le 0.2 \text{ V} \end{vmatrix}$	 A11 	1, 2, 3		 4.0 	mA -
		lone bit toggling, OEA = OEB = GND 4/ 	A11 	1, 2, 3		5.0 	l mA 	
Input capacitance	CIN	 		 A11	4		10	l pF
Output capacitance	COUT	 See 4.3.1c 		A11	4		12	pF
Functional tests		 See 4.3.1d		A11	7,8			
Propagation delay time, Dn to On	ltpLH,	C _L = 50 pF, R _L = 500Ω, 5/		01	9, 10, 11	1.5	7.0	ns
	see figu			02	j	1.5	5.1	
Output enable time, OEA, OEB to On	t _{P71}	C _L = 50 pF, R _L = 500Ω,		01	9, 10, 11	1.5	8.5	ns
	+	lsee figure 4 - 5/		02	<u> </u>	1.5	6.5	
Output disable time, OEA, OEB to On	tpHZ,	<u>' </u>		01	9, 10, 11	1.5	7.5	ns
				j 02 j	i	1.5	5.9	

 $[\]underline{1}$ / Not more than one output should be shorted at one time, and the duration of the short circuit condition should not exceed 1 second.

- 2/ TTL driven input ($V_{IN} = 3.4$ V); all other inputs at V_{CC} or GND.
- $\underline{3}$ / This parameter is not directly testable, but is derived for use in total power supply calculations.
- $\frac{4}{I_{CC}} = I_{CCQ} + (\Delta I_{CC} \times D_H \times N_T) + (I_{CCD} \times f_I \times N_I)$ where:

 D_H = Duty cycle for TTL inputs high N_T = Number of TTL inputs at D_H f_I = Input frequency in MHz N_I = Number of inputs at f_I

5/ The minimum limits are guaranteed, if not tested, to the limits specified in table I.

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Device types 01 and 02 Case outlines | R, S, 2 Terminal Terminal number symbol 0EA 1 2 3 DAO OBO DA1 081 6 7 DA2 0B2 8 DA3 9 0B3 10 11 12 13 14 15 GND DB3 0A3 DB2 0A2 DB1 16 0A1 17 DB0 18 0A0 19 0EB 20 **VCC**

FIGURE 1. Terminal connections.

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■CT THEFT

	Inputs	Output	
I OEA	l OEB		
 L L H	H H L	l L l H	L H Z

H = High voltage level
L = Low voltage level

X = Irrelevant

Z = High impedence

FIGURE 2. <u>Truth table</u>.

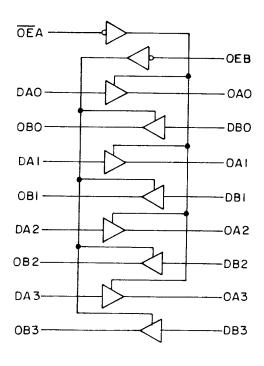


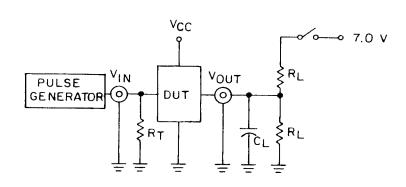
FIGURE 3. Logic diagram.

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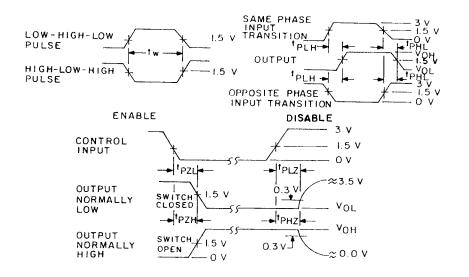
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 R_L = Load resistor, see ac characteristics for value. C_L = Load capacitance, includes probe and jig capacitance. See ac characteristics for value.

 R_T = Termination should be equal to Z_{OUT} of pulse generators.



NOTES:

- Diagram shown for input control enable, low and input control disable, high. Pulse generator for all pulses: tf \leq 2.5 ns, tr \leq 2.5 ns.

FIGURE 4. Test circuit and switching waveforms.

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- 3.6 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-BUL-103 (see 6.6 herein). The certificate of compliance submitted to DESC-ECS prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.
- 3.7 Certificate of conformance. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.
- 3.8 Notification of change. Notification of change to DESC-ECS shall be required in accordance with MIL-STD-883 (see 3.1 herein).
- 3.9 <u>Verification and review</u>. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
 - 4. QUALITY ASSURANCE PROVISIONS
- 4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).
- 4.2 <u>Screening</u>. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
 - a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.6 herein).
 - (2) $T_A = +125^{\circ}C$, minimum.
 - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
- 4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.
 - 4.3.1 Group A inspection.
 - a. Tests shall be as specified in table II herein.
 - b. Subgroups 5 and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.
 - c. Subgroup 4 (C_{IN} and C_{OUT} measurements) shall be measured only initially and after process or design changes which may affect capacitance. Test all applicable pins on 5 devices with zero failures.
 - d. Subgroups 7 and 8 tests shall verify the truth table as specified on figure 2.

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TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups Subgroups (per method 5005, table I)
 Interim electrical parameters (method 5004) 	
 Final electrical test parameters (method 5004) 	1*, 2, 3, 7, 8, 9, 10, 11
 Group A test requirements (method 5005) 	1, 2, 3, 4, 7, 8, 9, 10, 11
 Groups C and D end-point electrical parameters (method 5005)	1, 2, 3

^{*} PDA applies to subgroup 1.

4.3.2 Groups C and D inspections.

- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test conditions, method 1005 of MIL-STD-883.
 - Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.6 herein).
 - (2) $T_A = +125^{\circ}C$, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.
- PACKAGING
- 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.
 - 6. NOTES
- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.
- 6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

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- 6.3 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-481 using DD Form 1693, Engineering Change Proposal (Short Form).
- 6.4 Record of users. Military and industry users shall inform Defense Electronics Supply Center when a system application requires configuration control and the applicable SMD. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of the drawing covering microelectronics devices (FSC 5962) should contact DESC-ECS, telephone (513) 296-6022.
- 6.5 Comments. Comments on this drawing should be directed to DESC-ECS, Dayton, Ohio 45444, or telephone (513) 296-5375.
- 6.6 Approved source of supply. An approved source of supply is listed in MIL-BUL-103. Additional sources will be added to MIL-BUL-103 as they become available. The vendor listed in MIL-BUL-103 has agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DESC-ECS. The approved source of supply listed below is for information purposes only and is current only to the date of the last action of this document.

T		
Military drawing part number	Vendor CAGE number	Vendor similar part number 1/
 5962-8973201RX 	 61772 75569	IDT54FCT241DB P54PCT241DMB
5962-8973201SX	 61772 75569	IDT54FCT241EB P54PCT241FMB
5962-89732012X	61772 75569	IDT54FCT241LB P54PCT241LMB
5962-8973202RX	61772 75569	IDT54FCT241ADB P54PCT241ADMB
5962-8973202SX	61772 75569	IDT54FCT241AEB P54PCT241AFMB
 5962-89732022X 	61772 75569	IDT54FCT241ALB P54PCT241ALMB

1/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

SIZE

Vendor CAGE number

Vendor name and address

61772

Integrated Device Technology 3236 Scott Boulevard Santa Clara, CA 95052

75569

Performance Semiconductor Corporation 610 East Weddell Drive Sunnyvale, CA 94089

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